

## Description

The 832HT High Temperature Epoxy Encapsulating and Potting Compound is an electronic grade epoxy designed for high temperature environments. It is also an ideal encapsulant for very chemically aggressive environments and applications where extreme physical strength is required.

It protects against static discharges, shocks, vibrations, and mechanical impacts. It is extremely resistant to environmental humidity, salt water, and harsh chemicals. It also helps hide and restrict access to intellectual property, and it much harder to remove than standard epoxy encapsulating compounds.

## Applications & Usages

The 832HT epoxy is used to pot or encapsulate printed circuit assemblies in a protective block. The cured epoxy improves reliability, operational range, and lengthens the life of electrical and electronic parts.

Its primary applications involve protecting electronic devices in high temperature and chemically aggressive environments in the automobile, marine, aerospace, aviation, communication, instrumentation, and industrial control equipment.

## Benefits

- **High service temperature range** of 200 °C [392 °F]
- **Very strong chemical resistance**
- Extremely strong Bis F epoxy compared to standard Bis A epoxy systems
- **Mix ratio 2A:1B**, compatible with most dispensing equipment
- **Extreme resistance to water and humidity** allowing submersion if needed
- **Great intellectual property defense**: the cured epoxy hides parts and defies removal attempts
- **Protects electronics from** moisture, corrosion, fungus, thermal shock, and static discharges
- **Suitable for extreme environments** to brine, acids, bases, and aliphatic hydrocarbons

## Curing & Work Schedule<sup>a</sup>

Properties	Value
Working Life	60 minute
Shelf Life	5 year
Full Cure (at 20°C [68 °F])	24 hour
Full Cure (at 65°C [149 °F])	60 minute
Full Cure (at 80°C [176 °F])	45 minute
Full Cure (at 100°C [212 °F])	35 minute
Full Cure (at 130°C [266 °F])	25 minute
Full Cure (at 160°C [320 °F])	15 minute
Full Cure (at 200°C [392 °F])	10 minute

a) Working life and full cure assumes room temperature and 100g. A 10 °C increase can decrease the pot life by half.

Properties	Value
Storage Temperature of Unmixed Parts	16 to 27 °C [60 to 80 °F]

## Service Ranges

Properties	Value
Service Temperature	-30 to +200 °C [-22 to +392 °F]
Max Intermittent Temp. (short exposures only)	-40 to +250 °C [-40 to 482 °F]

# High Temperature Epoxy Encapsulating & Potting Compound 832HT Technical Data Sheet

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## Principal Components

### Name

Part A: Novalac Bis F Epoxy Resin  
Part B: Curing polyamide  
Curing Amine

### CAS Number

28064-14-4  
68082-29-1  
112-24-3

## Properties of Cured 832HT

<i>Physical Properties</i>	<i>Method</i>	<i>Value<sup>a</sup></i>
Color	Visual	Black
Density (at 23 °C [73.4 °C])		1.16 g/cm <sup>3</sup>
Hardness	(Shore D durometer)	87D
Elongation	ASTM D 638	3.38%
Tensile Strength	"	54.22 N/mm <sup>2</sup> [7,864 lb/in <sup>2</sup> ]
Compression Strength	ASTM D 695	81.84 N/mm <sup>2</sup> [11,870 lb/in <sup>2</sup> ]
Lap Shear Strength	ASTM D 1002	12.37 N/mm <sup>2</sup> [1,794 lb/in <sup>2</sup> ]
Flexural Strength	ASTM D 790	100.66 N/mm <sup>2</sup> [14,600 lb/in <sup>2</sup> ]
Flexural Modulus	"	2,751 N/mm <sup>2</sup> [399,000 lb/in <sup>2</sup> ]
<i>Electric Properties<sup>b</sup></i>	<i>Method</i>	<i>Value</i>
Breakdown Voltage @0.630 mm	ASTM D 149	26.4 kV
Dielectric Strength	"	44.82 kV/mm [1138 V/mil]
Breakdown Voltage @3.175 mm [1/8"]	Reference fit <sup>b</sup>	56.8 kV
Dielectric Strength		17.9 kV/mm [454 V/mil]
Volume Resistivity	ASTM D 257	9.3 x10 <sup>15</sup> Ω·cm
Surface Resistivity <sup>c</sup>	"	8.9 x10 <sup>13</sup> Ω
Dielectric Dissipation & Constant		<i>dissipation, D</i> <i>constant, k'</i>
@1 kHz	ASTM D 150-98	0.007      2.96
@10 kHz	"	0.011      2.81
@100 kHz	"	0.014      2.83
@1 MHz	"	0.014      2.83
Insulating		Yes
Conductive		No

*Note:* Specifications are for epoxy samples cured at 65 °C for 1 hour, with additional curing time at room temperature for optimal results. For most tests, samples were conditioned at 23 °C and 50% RH.

a) N/mm<sup>2</sup> = mPa; lb/in<sup>2</sup> = psi;

b) To allow comparison between products, the Tautscher equation was fitted to 10 experimental dielectric strengths and interpolated for a standard reference thickness of 1/8" (3.175 mm).

c) The surface (sheet) resistivity unit is commonly referred to as "Ohm per square" (Ω/sq)

## Properties of Cured 832HT (*Continued*)

<i>Thermal Properties</i>	<i>Method</i>	<i>Value</i>
Thermal Conductivity @25 °C [77 °C]	ASTM E 1461 92	0.218 W/m·K
Glass Transition Temperature		68 °C
Coefficient of Thermal Expansion	ASTM D 638 02a	
	-40 °C to +50 °C	75.7 ppm/°C
	+25 °C to +250 °C	140.2 ppm/°C
	+100 °C to +250 °C	154.0 ppm/°C
Overall CTE <sup>d</sup>	-40 °C to +250 °C	125.3 ppm/°C
Thermal Diffusivity @25 °C [77 °C]	"	$1.33 \times 10^{-7} \text{ m}^2/\text{s}$
Specific Heat Capacity @25 °C [77 °C]	ASTM E 1269 01	1419 J/(kg·K)
Heat Deflection Temperature <sup>e</sup>	ASTM D 648	53.9 °C [129 °F]

d) Coefficient of Thermal Expansion (CTE) units are in ppm/°C = in/in/°C × 10<sup>-6</sup> = unit/unit/°C × 10<sup>-6</sup>

e) HDT of plastic under load of 264 lb/in<sup>2</sup>

## Properties of Uncured 832HT

<i>Physical Property</i>	<i>Mixture (2A:1B)</i>	
Color	Black	
Viscosity <sup>a</sup> at 20 °C [73 °F]	40,000 cP [40.0 Pa·s]	
Density	1.12 g/mL	
Mix Ratio by weight (A:B)	2.0:1	
Mix Ratio by volume (A:B)	1.7:1	


<i>Physical Property</i>	<i>Part A</i>	<i>Part B</i>
Color	Black	Clear, amber tint
Viscosity <sup>a</sup> at 24°C [73 °F]	46 000 cP [46.0 Pa·s]	5 800 cP [5.8 Pa·s]
Density	1.198 g/mL	0.963 g/mL
Flash Point	150 °C [302 °F]	110 °C [230 °F]
% solids	~98%	100%
Odor	Mild	Musty

a) Brookfield viscometer at 50 RPM with spindle LV4

## Compatibility

**Adhesion**—As seen in the substrate adhesion table, the 832HT epoxy adheres to most materials found on printed circuit assemblies; however, it is not compatible with contaminants like water, oil, and greasy flux residues that may affect adhesion. If contamination is present, clean the printed circuit assembly with electronic cleaner such as MG Chemicals 4050 Safety Wash, 406B Superwash, or 824 Isopropyl Alcohol.

## Substrate Adhesion in Decreasing Order

<i>Physical Properties</i>	<i>Adhesion</i>
Aluminum	Stronger
Steel	
Fiberglass	
Wood	
Paper, Fiber	
Glass	
Rubber	
Polycarbonate	
Acrylic	
Polypropylene <sup>a</sup>	
	Weaker

a) Does not bond to polypropylene

## Storage

Store between 16 and 27 °C [60 and 80 °F] in dry area away from sunlight. Prolonged storage or storage at or near freezing temperatures can result in crystallization. If crystallization occurs, reconstitute the component to its original state by temporarily warming it to 50 to 60 °C [122 to 140 °F]. To ensure full homogeneity, stir thoroughly the warm component, reincorporating all settled material. Re-secure container lid and let cool down before use.

## Health and Safety

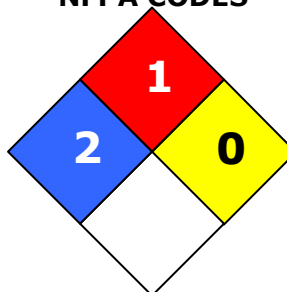
Please see the 832HT **Material Safety Data Sheet** (MSDS) parts A and B for more details on transportation, storage, handling and other security guidelines.

### Part A

#### HMIS RATING

<b>HEALTH:</b>	<b>2</b>
<b>FLAMMABILITY:</b>	<b>1</b>
<b>PHYSICAL HAZARD:</b>	<b>0</b>
<b>PERSONAL PROTECTION:</b>	

#### NFPA CODES

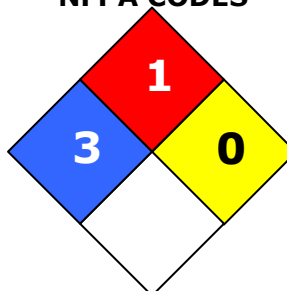


### Part B

#### HMIS RATING

<b>HEALTH:</b>	<b>3</b>
<b>FLAMMABILITY:</b>	<b>1</b>
<b>PHYSICAL HAZARD:</b>	<b>0</b>
<b>PERSONAL PROTECTION:</b>	<b>B</b>

#### NFPA CODES



**Health and Safety:** The 832HT parts can ignite if the liquid is both heated and exposed to flames or sparks.

Wear safety glasses or goggles and disposable polyvinyl chloride, neoprene, or nitrile gloves while handling liquids. Part B in particular causes skin burns and may cause sensitization if exposed over a long period of time. The epoxy is black and will not wash off once cured: wear protective work clothing. Wash hands thoroughly after use or if skin contact occurs. Do not ingest.

Use in well-ventilated area since vapors may cause irritation of the respiratory tract and cause respiratory sensitization in susceptible individuals.

The cured epoxy resin presents no known hazard.

## Application Instructions

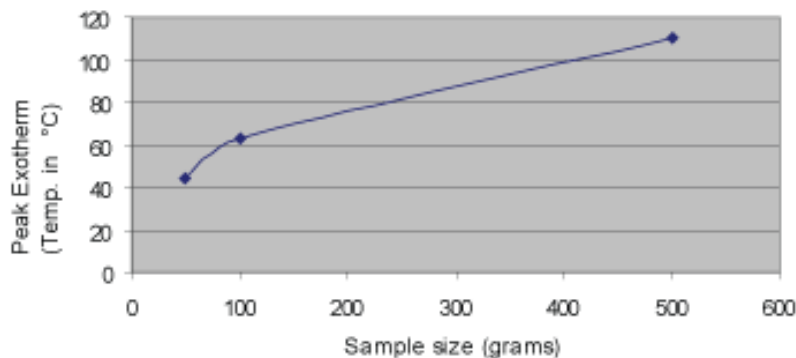
Follow the procedure below for best results. If you have little or no experience with the 832HT epoxy, please follow the long instructions instead. The short instructions provided here are not suitable for first time users.

### To prepare 2:1 (A:B) epoxy mixture

1. Stir and fold the material in the **Part A** container until fully homogenous.
2. With a different stirrer, stir and fold the material in the **Part B** container until fully homogenous.
3. Measure **two** parts by volume (or weight) of pre-stirred **A**, and pour in the mixing container.
4. Measure **one** part by volume (or weight) of pre-stirred **B**, and slowly pour in the mixing container while stirring.
5. Put in a vacuum chamber, bring to 25 Hg/in pressure, and wait for 2 minutes to de-air.  
—OR—  
Let sit for 30 minutes to de-air.
6. If bubbles are present at top, use the mixing paddle to gently break them.
7. Pour mixture into the mold or container containing the components to be encapsulated.

**ATTENTION!** Mixing >500 g [0.4 L] of Part B at a time into A decreases working life and promotes flash cure. Use of epoxy mixing machines with static stirrer recommended for large volumes. Limit size of hand-mixed batches.

### Peak Exotherm Temperature



### To room temperature cure the 832HT epoxy

Let stand for 24 hours.

## To heat cure the 832HT epoxy

Put in oven at 65 °C [149 °F] for 60 minutes.

–OR–

Put in oven at 80 °C [176 °F] for 45 minutes.

–OR–

Put in oven at 100 °C [212 °F] for 35 minutes.

–OR–

Put in oven at 130 °C [266 °F] for 25 minutes.

–OR–

Put in oven at 160 °C [320 °F] for 15 minutes.

–OR–

Put in oven at 200 °C [392 °F] for 10 minutes.

## **ATTENTION!**

Due to exothermic reaction, heat cure temperatures should be at least 25% below the maximum temperature tolerated by the most fragile PCB component. For larger potting blocks, reduce heat cure temperature by greater margins.



ISO 9001 Registered Quality System.  
Burlington, Ontario, Canada QMI File # 004008

# High Temperature Epoxy Encapsulating & Potting Compound 832HT Technical Data Sheet

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## Packaging and Supporting Products

### Product Availability

<i>Cat. No.</i>	<i>Form</i>	<i>Net Volume</i>		<i>Net Weight</i>		<i>Shipping Weight</i>	
<b>832HT-375ML</b>	Liquid	0.375 L	12 oz	.44 kg	1.0 lb	0.6 kg	1.3 lb
<b>832HT-3L</b>	Liquid	3.0 L	0.8 gal	3.46 kg	7.6 lb	3.9 kg	8.5 lb

### Supporting Products

- 8328 Epoxy and Adhesive Cleaner
- 8329 Epoxy Mold Release (for temperature cures  $\leq 85$  °C)

## Technical Support

Contact us regarding any questions, improvement suggestions, or problems with this product. Application notes, instructions, and FAQs are located at [www.mgchemicals.com](http://www.mgchemicals.com).

Email: [support@mgchemicals.com](mailto:support@mgchemicals.com)

Phone: 1-800-340-0772 Ext. 30 (Canada, Mexico & USA)

1-905-331-1396 Ext. 30 (International)

Fax: 1-905-331-2862 or 1-800-340-0773

Mailing address: **Manufacturing & Support**  
1210 Corporate Drive  
Burlington, Ontario, Canada  
L7L 5R6

**Head Office**  
9347-193rd Street  
Surrey, British Columbia, Canada  
V4N 4E7

## Warranty

*M.G. Chemicals Ltd.* warrants this product for 12 months from the date of purchase by the end user. *M.G. Chemicals Ltd.* makes no claims as to shelf life of this product for the warranty. The liability of *M.G. Chemicals Ltd.* whether based on its warranty, contracts, or otherwise shall in no case include incidental or consequential damage.

## Disclaimer

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